

**Preliminary Amendment**

Applicant: Wolfgang Hetzel et al.

Serial No.: Unknown

(Priority Application No. DE 103 50 239.4 )

(International Application No. PCT/DE2004/002374)

Filed: Herewith

(Priority Date: October 27, 2003 )

(International Filing Date: October 25, 2004)

Docket No.: I431.156.101/FIN546PCT/US

Title: SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING COMPOUND,  
SEMICONDUCTOR CHIP AND LEADFRAME AND METHOD FOR PRODUCING THE SAME

---

**IN THE SPECIFICATION**

Please insert the following paragraph beginning at page 1, line 5, of the substitute specification with the following paragraph:

**Cross Reference to Related Application**

This Utility Patent Application claims the benefit of the filing date of German Application No. DE 103 50 239.4, October 27, 2003, and International Application No. PCT/DE2004/002374, filed October 25, 2004, both of which are herein incorporated by reference.